

SEMICON® WEST 2022 SHOW DAILY

SEMICONDUCTOR **DIGEST**

EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100% die transfer yield on multi-die 3D SoC – July 13, 2022

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July 13, 2022



ARM PURIFICATION
BY APPLIED ENERGY SYSTEMS

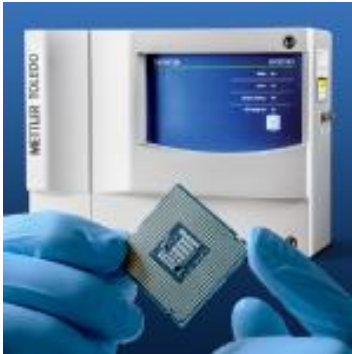
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Proven Purifier Solutions
Uphold Purity Requirements for
Stringent Applications

Day Two

- [Don't miss today's Show Daily](#)
- [Onto Innovation wins 2022 Best of West Award for Atlas V optical critical dimension metrology tool](#)
- [Shortage to surplus cycle hits semi but one segment escapes](#)
- [Global total semiconductor equipment sales on track to record \\$118B in 2022](#)
- [EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100% die transfer yield on multi-die 3D SoC](#)
- [ClassOne Technology announces new surface preparation technology that extend the Solstice single-wafer platform](#)
- [20-year roadmap: Tearing down the walls](#)

- [SEMI announces election and re-election of board members](#)



[Improve Wafer Quality and Yield](#)

The METTLER TOLEDO 6000TOCi delivers continuous real-time TOC monitoring at sub-ppb levels while reducing sample water usage by up to 90%. Optimize wafer yield and reduce defects while meeting green initiatives to limit wasted water. Improve yield and UPW Reclaim/Reuse/Recycle control with the 6000TOCi. [Learn more.](#)

Top Stories

[Don't miss today's Show Daily](#)

SEMICON West Day 2 – Sustainability Summit keynotes feature Applied Materials, ASML, EMD Electronics, IBM, Intel, Kleiner Perkins, and TSMC. Join us for TechTALKS on MEMS & Sensors and Heterogeneous Integration, and Test Vision Symposium.

Visit the FLEX Conference in South Hall, Lower Lobby and Design Automation Conference Expo (DAC) in Moscone West. Check out Meet the Experts Theaters at Workforce Development, Manufacturing, and Mobility Pavilions.

Get connected face-to-face with the industry at tonight's networking events – ESD Alliance, FLEX, Global Automotive Advisory Council (GAAC), Heterogeneous Integration, MEMS & Sensors Industry Group (MSIG), Silicon Manufacturers Group (SMG), Test Vision, and Workforce Development receptions. [More>>](#)

[Onto Innovation wins 2022 Best of West Award for Atlas V optical critical dimension metrology tool](#)

The Atlas V optical critical dimension metrology tool from Onto Innovation, Inc. has won the 2022 Best of West award, SEMI and Semiconductor Digest announced

today at SEMICON West 2022 Hybrid, July 12-14 at the Moscone Center in San Francisco. [More>>](#)

Shortage to surplus cycle hits semi but one segment escapes

One major part of the semiconductor industry is escaping the downward trend felt by the larger market. But this time, it's different. [More>>](#)

Global total semiconductor equipment sales on track to record \$118B in 2022

Global sales of total semiconductor manufacturing equipment by original equipment manufacturers are forecast to reach a record \$117.5 billion in 2022. [More>>](#)



Magnetically Levitated Turbopumps

Pfeiffer Vacuum ATH 2804 M/MT and ATH 3204 M/MT magnetically levitated turbopumps are designed for harsh semiconductor applications. They offer a gas throughput of over 5,000 sccm of nitrogen for non-heated applications and up to 1,500 sccm of argon at 65°C in corrosive applications. To prevent by-product deposition, the MT model can be heated and regulated up to 85°C. Visit Pfeiffer Vacuum at SEMICON West, booth 1329. [Learn more.](#)

New Products & Technologies

EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100% die transfer yield on multi-die 3D SoC

EV Group announced it has achieved a major breakthrough in die-to-wafer (D2W) fusion and hybrid bonding by successfully demonstrating 100-percent void-free bonding yield of multiple die of different sizes from a complete 3D system-on-a-chip (SoC) in a single transfer process using EVG's GEMINI FB automated hybrid bonding system. [More>>](#)

603-547-5309

sdavis@semiconductordigest.com

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NEWS AND INDUSTRY TRENDS
JULY 2022

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EMERGING METROLOGY REQUIREMENTS FOR HETEROGENEOUS INTEGRATION AND 3D PACKAGING



**GOLD FLAG
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